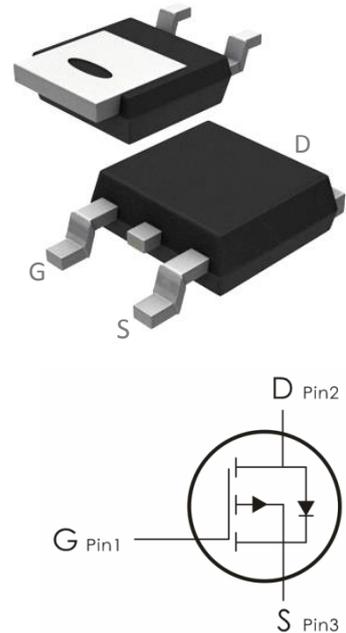


Description:

This P-Channel MOSFET uses advanced trench technology and design to provide excellent $R_{DS(on)}$ with low gate charge. It can be used in a wide variety of applications.

Features:

- 1) $V_{DS}=-30V, I_D=-25A, R_{DS(ON)}<35m\ \Omega @V_{GS}=-10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra $R_{DS(ON)}$.
- 5) Excellent package for good heat dissipation.



Absolute Maximum Ratings: ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current	-25	A
	Continuous Drain Current- $T_C=100^\circ\text{C}$	-19	
	Pulsed Drain Current ¹	-60	
E_{AS}	Single Pulse Avalanche Energy	30	mJ
P_D	Power Dissipation	40	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	2.6	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	-	

Package Marking and Ordering Information:

Part NO.	Marking	Package
DC033PG	C033P	TO-252

Electrical Characteristics: ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\ \mu\text{A}$	-30	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS}=0V, V_{DS}=-30V, T_J=25^\circ\text{C}$	---	---	-1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0A$	---	---	± 100	nA
On Characteristics						
$V_{GS(th)}$	GATE-Source Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\ \mu\text{A}$	-1.0	-1.6	-2.5	V
$R_{DS(on)}$	Drain-Source On Resistance	$V_{GS}=-10V, I_D=-8A$	---	---	35	$m\ \Omega$
		$V_{GS}=-4.5V, I_D=-5A$	---	---	60	
G_{FS}	Forward Transconductance	$V_{DS}=-5V, I_D=-18A$	---	18	---	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=-15V, V_{GS}=0V, f=1\text{MHz}$	---	660	---	μF
C_{oss}	Output Capacitance		---	100	---	
C_{rss}	Reverse Transfer Capacitance		---	65	---	
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time ^{2,3}	$V_{DS}=-15V, I_D=-4A,$ $R_{GEN}=3\ \Omega, V_{GS}=-10V$	---	7.5	---	ns
t_r	Rise Time ^{2,3}		---	5.6	---	ns
$t_{d(off)}$	Turn-Off Delay Time ^{2,3}		---	19	---	ns
t_f	Fall Time ^{2,3}		---	6	---	ns
Q_g	Total Gate Charge ^{2,3}	$V_{GS}=-10V, V_{DS}=-15V,$ $I_D=-6.5A$	---	9.2	---	nC
Q_{gs}	Gate-Source Charge ^{2,3}		---	1.6	---	nC
Q_{gd}	Gate-Drain "Miller" Charge ^{2,3}		---	2.2	---	nC
Drain-Source Diode Characteristics						
V_{SD}	Source-Drain Diode Forward Voltage ²	$V_{GS}=0V, I_S=-1A, T_J=25^\circ\text{C}$	---	---	-1.2	V

Notes:

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\cong 300\mu s$, duty cycle $\cong 2\%$.
3. Essentially independent of operating temperature.

Typical Characteristics: ($T_c=25^\circ C$ unless otherwise noted)

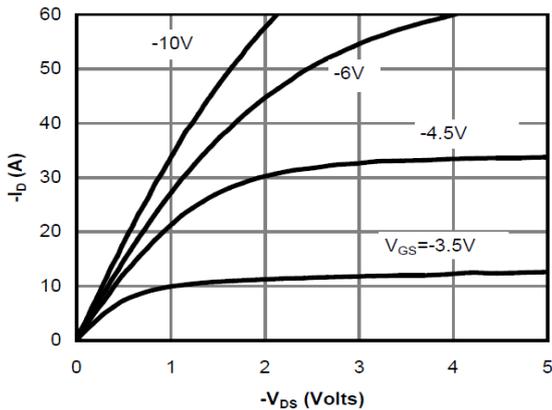


Figure 1: On-Region Characteristics

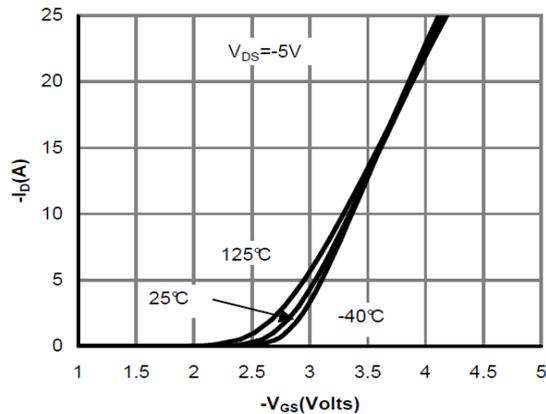


Figure 2: Transfer Characteristics

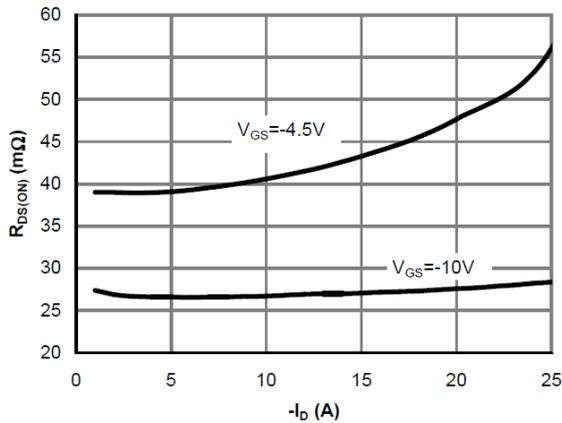


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

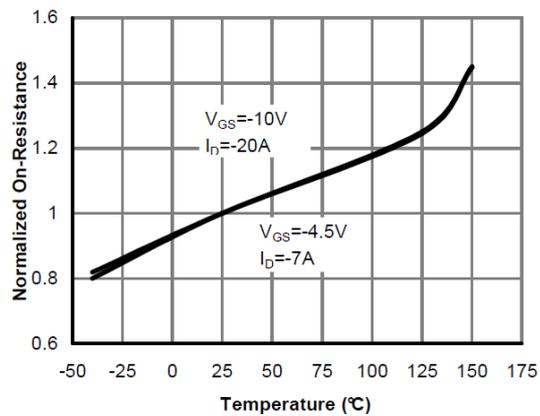


Figure 4: On-Resistance vs. Junction Temperature

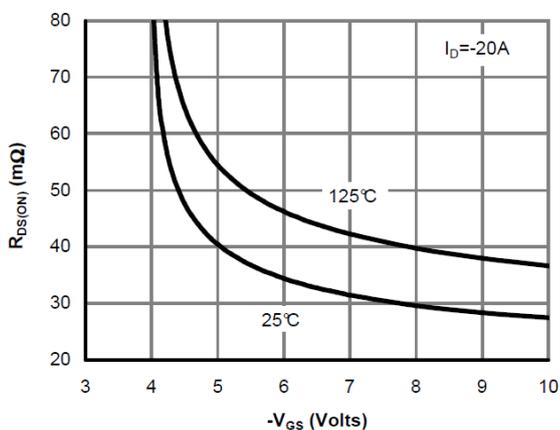


Figure 5: On-Resistance vs. Gate-Source Voltage

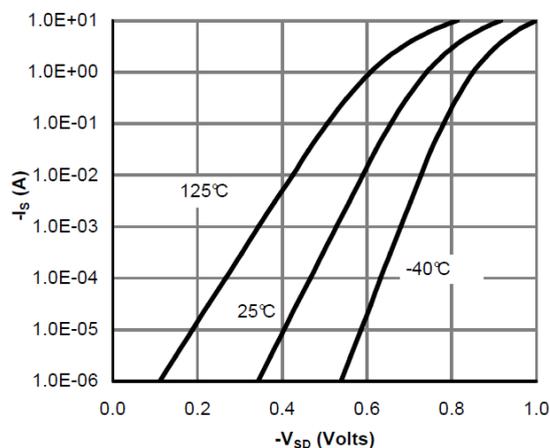


Figure 6: Body-Diode Characteristics

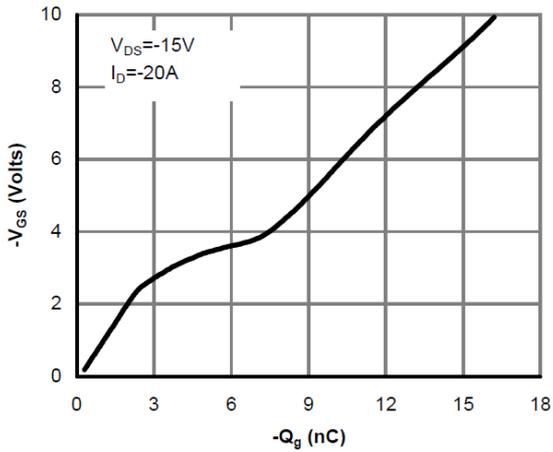


Figure 7: Gate-Charge Characteristics

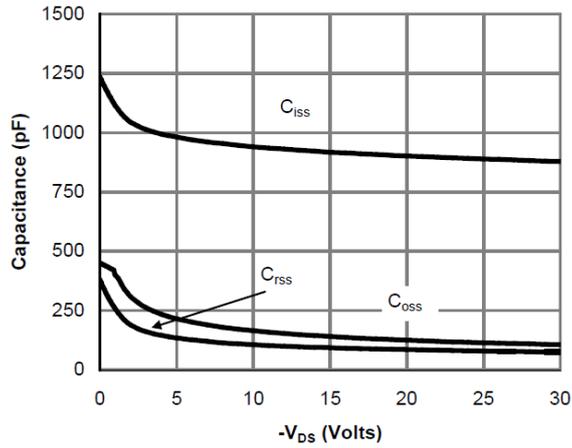


Figure 8: Capacitance Characteristics

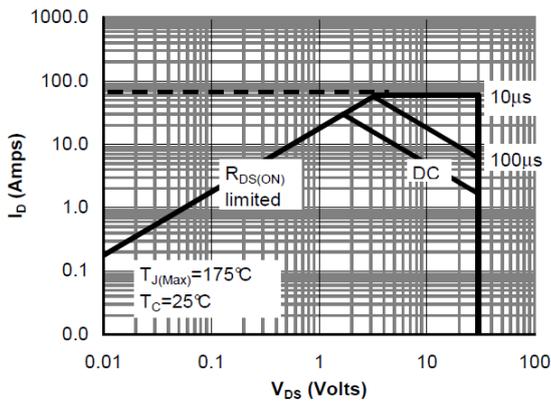


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

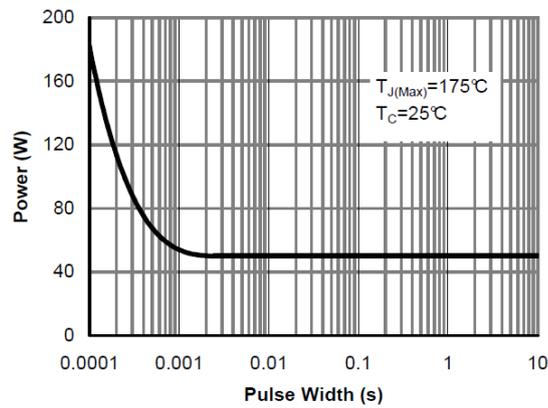


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

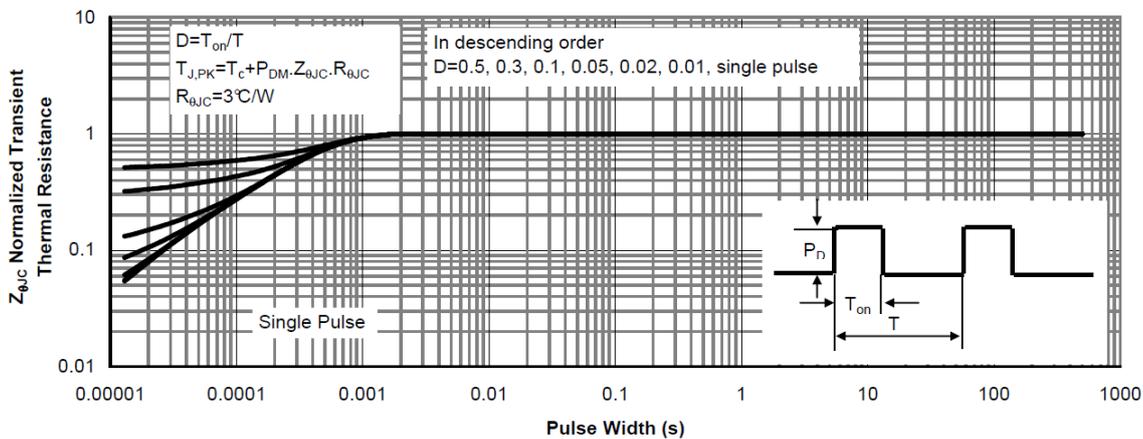


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)